Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1–10. (Canceled)

11. (Currently Amended) A wafer-holding carrier which is used when holding wafers between an upper turn table and a lower turn table to which polishing pads are attached, and polishing both sides of the wafers by a polishing agent, wherein the carrier has polishing agent-passing holes for passing the polishing agent through as well as wafer-holding holes for containing and holding the wafers, and the total area of the polishing agent-passing holes occupies more than 20% ~~15% or more~~ of a main surface of the carrier.

12. (Previously Presented) The wafer-holding carrier according to Claim 11, wherein the total area of the polishing agent-passing holes occupies 30% or less of the main surface of the carrier.

13. (Previously Presented) The wafer-holding carrier according to Claim 11, wherein each of the polishing agent-passing holes has a circular shape of a diameter of 5 mm – 30 mm.

14. (Previously Presented) The wafer-holding carrier according to Claim 12, wherein each of the polishing agent-passing holes has a circular shape of a diameter of 5 mm – 30 mm.

15–18. (Canceled)

19. (Previously Presented) A double-side polishing apparatus having at least an upper turn table and a lower turn table to which polishing pads are attached, a turn table-moving mechanism for moving the upper turn table and the lower turn table relatively, a carrier for holding wafers between the upper turn table and the lower turn table, and a carrier-moving mechanism for moving the carrier between the upper turn table and the lower turn table,

wherein the upper turn table is provided with a polishing agent-supplying hole for supplying a polishing agent, and the carrier is the wafer-holding carrier according to Claim 11.

20. (Previously Presented) The double-side polishing apparatus according to Claim 19, wherein the carrier-moving mechanism moves the wafer-holding carrier circularly without rotation in a plane of the carrier to revolve the wafers held in the wafer-holding holes and between the upper turn table and the lower turn table.

21. (Previously Presented) The double-side polishing apparatus according to Claim 19, wherein hardness of the polishing pad is Shore A 50 or more.

22. (Previously Presented) The double-side polishing apparatus according to Claim 20, wherein hardness of the polishing pad is Shore A 50 or more.

23. (Previously Presented) The double-side polishing apparatus according to Claim 19, wherein material of the polishing pad is urethane or rubber.

24. (Previously Presented) The double-side polishing apparatus according to Claim 20, wherein material of the polishing pad is urethane or rubber.

25. (Previously Presented) The double-side polishing apparatus according to Claim 21, wherein material of the polishing pad is urethane or rubber.

26. (Previously Presented) The double-side polishing apparatus according to Claim 22, wherein material of the polishing pad is urethane or rubber.

27. (Previously Presented) A method for polishing both sides of wafers comprising using the double-side polishing apparatus according to Claim 19, containing wafers in the wafer-holding holes of the carrier arranged between the upper turn table and the lower turn table, moving the upper turn table and the lower turn table relatively while supplying a polishing agent from the upper turn table side, and moving the carrier between the upper turn table and the lower turn table, thereby to polish the both sides of the wafers.

28. (Previously Presented) A method for polishing both sides of wafers comprising using the double-side polishing apparatus according to Claim 20, containing wafers in the wafer-holding holes of the carrier arranged between the upper turn table and the lower turn table, moving the upper turn table and the lower turn table relatively while supplying a polishing agent from the upper turn table side, and moving the carrier between the upper turn table and the lower turn table, thereby to polish the both sides of the wafers.

29. (Previously Presented) The method for polishing both sides of wafers according to Claim 27, wherein amount of the polishing agent supplied from the upper turn table side is from 3 liters/min to 10 liters/min.

30. (Previously Presented) The method for polishing both sides of wafers according to Claim 28, wherein amount of the polishing agent supplied from the upper turn table side is from 3 liters/min to 10 liters/min.

31. (New) The wafer-holding carrier according to Claim 11, wherein the polishing agent-passing holes are arranged in the form of concentric circle or lattice on the carrier entirely.

32. (New) The wafer-holding carrier according to Claim 12, wherein the polishing agent-passing holes are arranged in the form of concentric circle or lattice on the carrier entirely.

33. (New) The wafer-holding carrier according to Claim 13, wherein the polishing agent-passing holes are arranged in the form of concentric circle or lattice on the carrier entirely.

34. (New) The wafer-holding carrier according to Claim 14, wherein the polishing agent-passing holes are arranged in the form of concentric circle or lattice on the carrier entirely.